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	Applicant(s): Mitsuhiko Okada and Tomoaki Uchiya						
	Filing Date: 12/19/00		Group: Unknown				
U.S. PATENT DOCUMENTS							
Examiner Initial		Document Number	Date	Name	Class	SubClass	Filing Date If Appropriate
MOB		5,741,579	4/21/98	Nishizawa			
FOREIGN PATENT DOCUMENTS							
		Document Number	Date of Publication	Country	Class	SubClass	Translation
							Yes No
MOB		2061093 ✓	8/15/92	CA			X
MOB		0 499 585 ✓	8/19/92	EPO (English Abstract Attached)			X
MOB		0 528 606 ✓	2/24/93	EPO			
MOB		0 790 762 ✓	8/2/97	EPO			
MOB		0 928 027 ✓	7/7/99	EPO			
MOB		56-837	1/7/81	JP (English Abstract Attached)			X
MOB		6-291226 ✓	10/18/94	JP (English Abstract Attached)			X
MOB		7-111300 ✓	4/25/95	JP			X
MOB		7-157664 ✓	6/20/95	JP			X
MOB		8-174765 ✓	7/9/96	JP			X
MOB		9-17923 ✓	1/17/97	JP (English Abstract Attached)			X
MOB		10-189838 ✓	7/21/98	JP			X
MOB		10-204295 ✓	8/4/98	JP			X
MOB		WO 96/37915 ✓	11/28/96	PCT			
MOB		WO 99/05722 ✓	2/4/99	PCT			
MOB		WO 00/63968 ✓	10/26/00	PCT			
OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)							
MOB		Sasaski, Tomiya, et al., "Development of Sheet Type Thermal Conductive Compound Using Ain," Proceedings of the (Japan) International Electronic Manufacturing Technology Symposium, U.S., New York, IEEE, 12/4/1995, pp. 236-239, XP000686771					
MOB		Anonymous, "Filled Silicone Gel as a Thermal Transfer Medium in Electronic Packages," IBM Technical Disclosure Bulletin, vol. 30, no. 12, 5/1/88, p. 146, XP002158633					
EXAMINER 				Date Considered 2/7/02			

*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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